

AMENDMENT TO THE SPECIFICATION

Replace the existing abstract in its entirety with the following abstract:

--An integrated circuit chip having a contact layer that includes a plurality of Vdd, Vddx, ground and I/O contacts arranged in a generally radial pattern having diagonal and major axis symmetry and generally defining four quadrants. A multilayer X-Y power grid is located beneath the contact layer. A wiring layer is interposed between the contact layer and power grid to provide a well-behaved electrical transition between the generally radial Vdd, Vddx and ground contacts and the rectangular X-Y power grid. The interposed wiring layer includes concentric square rings of Vdd, Vddx and ground wires located alternately with one another. The Vddx wires are discontinuous between adjacent quadrants so that the magnitude of Vddx may be different in each quadrant of the chip if desired.--